



# Material Declaration Data Sheet

Model: **Server System MFSYS25, MFSYS35**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **No**

Date: February 27, 2009

## Restriction on Hazardous Substances (RoHS) Compliance

### RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

### RoHS Declaration

- 1** Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2** Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4** Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5** Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7** Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8** Lead used in compliant pin connector systems.
- 9** Lead as a coating material for the thermal conduction module c-ring.
- 10** Lead in optical and filter glass.
- 11** Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13** Cadmium in optical and filter glass.
- 14** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (\*) amending Directive 76/769/EEC (\*\*) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15** Lead in bronze bearing shells and brushes.
- 16** Lead in printing inks for application of enamels on borosilicate glass
- 17** Cadmium in printing inks for application of enamels on borosilicate glass
- 18** Lead in Finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames
- 19** Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
- 20** Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements: notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit, and frit ring as well as in print pastes.
- 21** Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

# Product Code Information



Product Code	Description	*RoHS Exemption #
AXXGBIOMEZ	Compute Module Mezzanine board	Compliant with no exemptions
AXXMFRAIL	Toolless rail kit	Compliant with no exemptions
AXXPSU	1000W Power Supply spare	1,2,3,4,5,6,7
AXXSCM3S	Intel® Multi-Flex Server Storage Module - SAS	Compliant with no exemptions
AXXSW1GB	Intel® Multi-Flex Server GbE Switch Switch	Compliant with no exemptions
MFBEZEL	10 pack standard HDD bay bezel	Compliant with no exemptions
MFCMM	Intel® Multi-Flex Server Management Module	Compliant with no exemptions
MFHDDBAY25	2.5" system 14 drive bay for 2.5 " HDD	Compliant with no exemptions
MFIOFAN	I/O fan module	Compliant with no exemptions
MFMAINFAN	Main fan module	Compliant with no exemptions
MFIDPLANE	Midplane board which includes SD Flash	Compliant with no exemptions
MFPSUFAN	Power Slot Cooling Module	Compliant with no exemptions
MFS5000SI	Intel® Multi-Flex Server Compute Module	Compliant with no exemptions
MFS5000SIB	Intel® Multi-Flex Server Compute Module-Bulk pack	Compliant with no exemptions
MFSCMBBU	Storage Battery Backup Unit for Storage Module	Compliant with no exemptions
MFSYS25	Entry system for 2.5" HDD - 6U chassis	1,2,3,4,5,6,7
MFSYS35	System for 3.5" HDD – 6U chassis	1,2,3,4,5,6,7
MFHDDBAY35	3.5" system 6 drive bay for 3.5" HDD	Compliant with no exemptions
FXX10DVCARBLK	HDD Drive Carrier, 10-pack	Compliant with no exemptions

\* RoHS Exemption # corresponds with exemption #'s found on page 1.